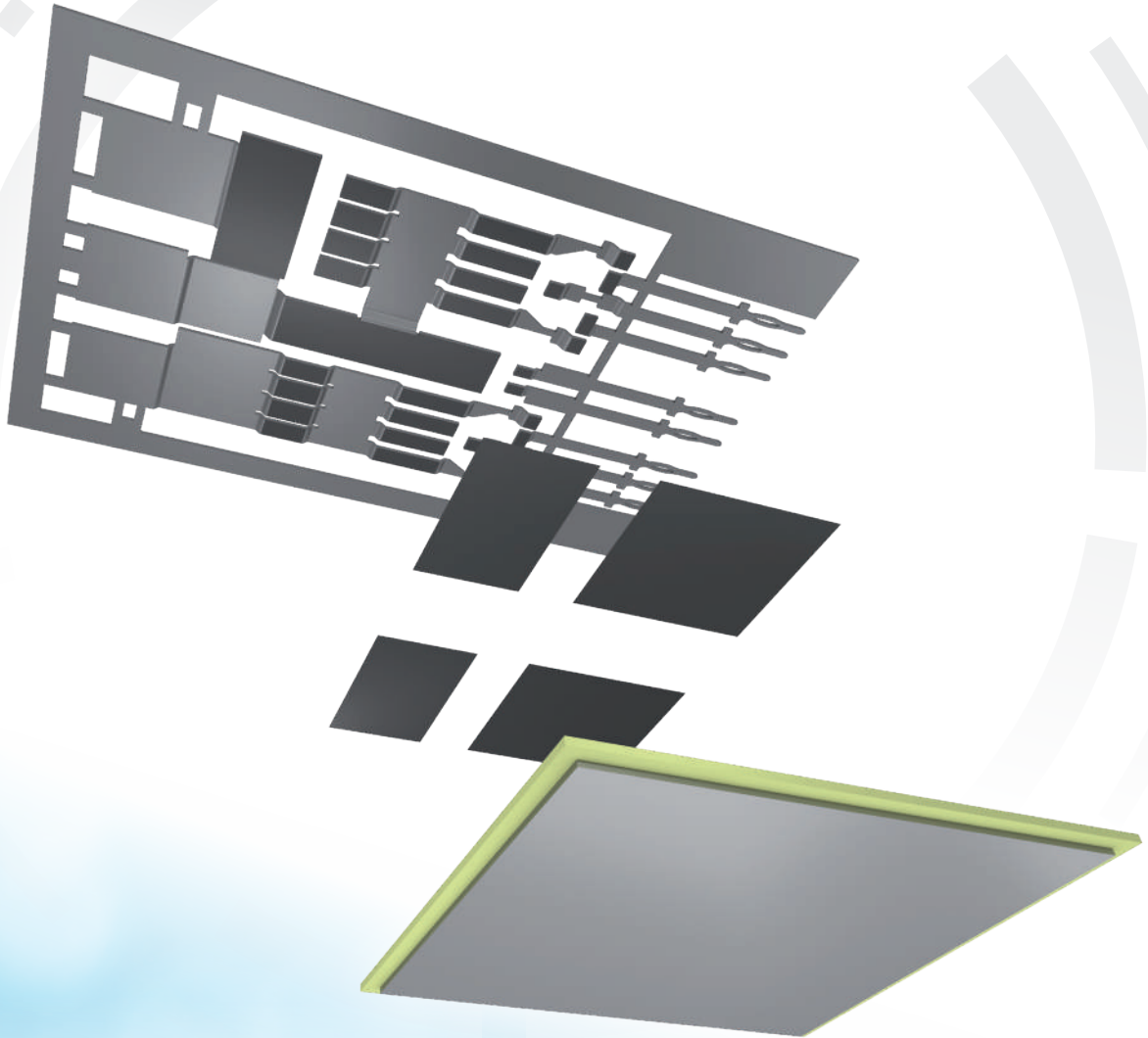
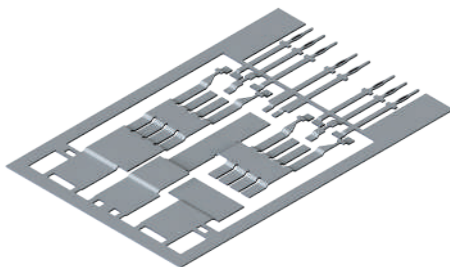


POWERFUL

TOP SIDE DIE-ATTACH SOLUTIONS

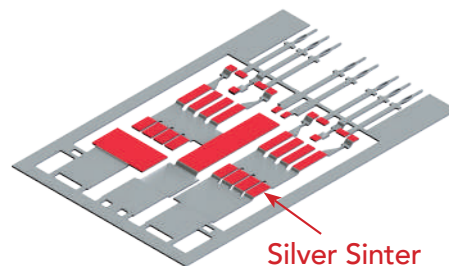


Interplex Sinter-PLX™
Sinter-bonded
Power Lead Frame Technology



Top

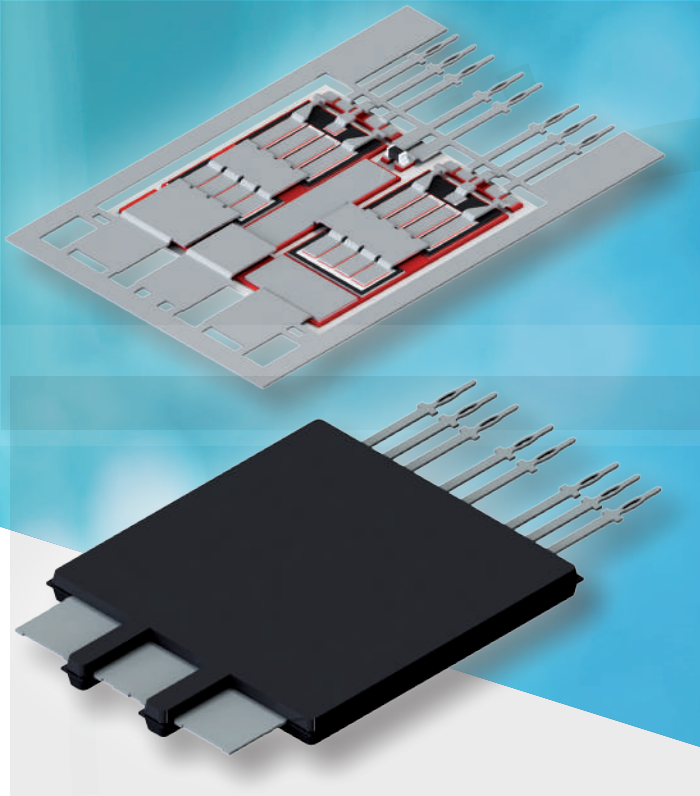
ALPHA® Argomax Film
Sinter Technology



Silver Sinter

Bottom with Bonded Silver Sinter

POWERFUL TOP SIDE DIE-ATTACH SOLUTIONS



Interplex Sinter-PLX™ Features and Benefits

- Selective-bonded silver sinter power lead frames
- Silver sinter for top side direct die attach
- 200 –300 W/mK conductivity
- Low-resistance silver sinter bond
- Efficient heat dissipation
- Low inductance
- Good adhesion flexible bond line

For more information, email us at communications@interplex.com

ALPHA® Argomax Features and Benefits

- Pure silver bond line for high reliability & performance
- Film format for ease of use in manufacturing
- Easy and reliable lamination
- Long shelf life at room temperature
- High thermal and electrical conductivity
- Low sintering pressure for high yield manufacturing
- Die attach temperatures suitable for semiconductor packaging

For more information, please scan the QR code



>30X
IMPROVED
reliability



>40%
REDUCTION IN
\$/kw



>40%
IMPROVED
efficiency



>50%
REDUCTION IN
development
T I M E

alpha 

 Interplex

* Pictures shown are for illustrative purposes only